
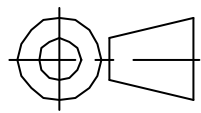
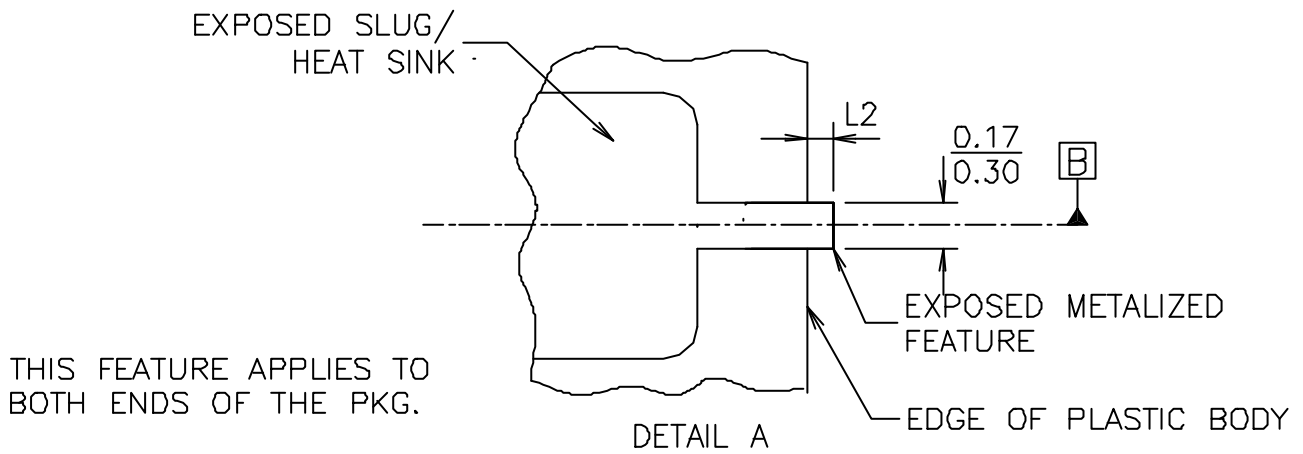
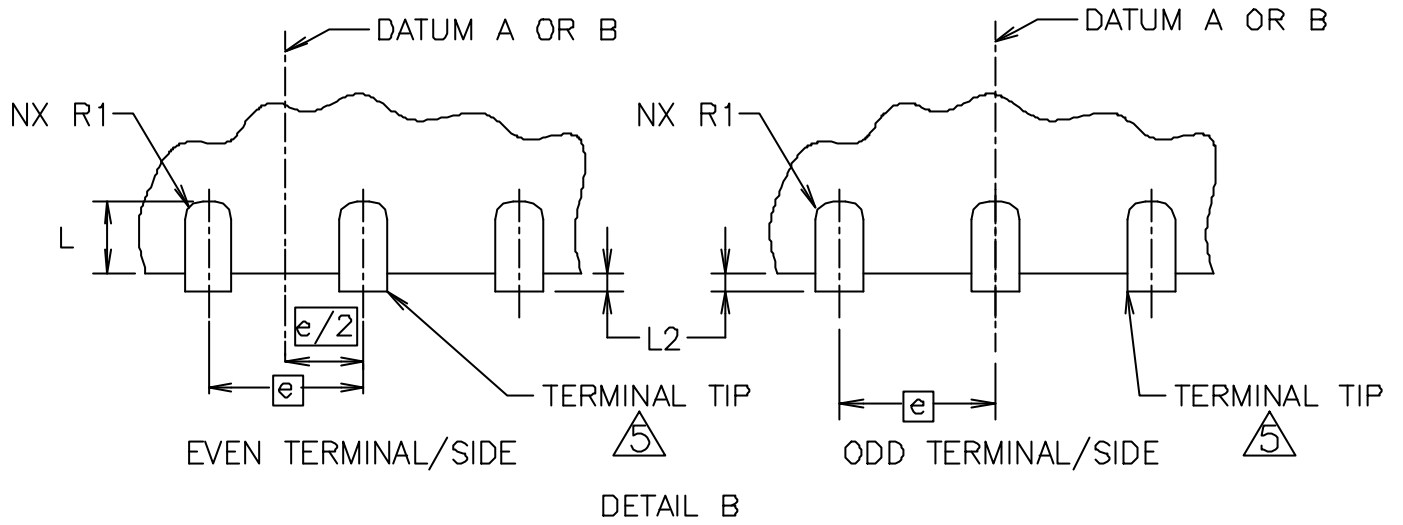


APPROVAL	SIGN	DATE
TOOLING MGR		
ENGG MGR		
OPERATIONS MGR		


FOR REVISION UPDATE PLEASE REFER TO HISTORY OF CHANGES.

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REV A	DWG NO: - MLPM-CPOD-0003		FILE:- MLPM-CPOD-0003-RevA
	APP'D -		MLP MICRO PACKAGE OUTLINE (EXPOSED & FUSED DUAL PAD)
	CHECKED CC YIP		PAGE 1 of 7
	DESIGNED -		
DRAWN KC LAU			

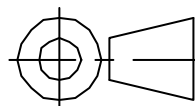


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DWG NO: - MLPM-CPOD-0003	
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FILE:- MLPM-CPOD-0003-RevA

MLP MICRO
PACKAGE OUTLINE
(EXPOSED & FUSED DUAL PAD)

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TABLE 1




VARIATION DESIGNATORS							
FIRST DIGIT CODE		SECOND DIGIT CODE		THIRD DIGIT CODE		FOURTH DIGIT CODE	
OVERALL HEIGHT		BODY LENGTH		BODY WIDTH		TERMINAL PITCH	
A	LETTER CODE	D	LETTER CODE	E	LETTER CODE	e	LETTER CODE
1.0 MAX	V	1.0	A	1.0	A	0.95	A
		1.5	B	1.5	B	0.65	C
		2.0	C	2.0	C	0.50	D
		2.5	D	2.5	D		
		3.0	E	3.0	E		

TABLE 2: TOLERANCE OF FORM AND POSITION

PITCH (MM) / SYMBOL	0.95	0.65	0.50
aaa	0.10	0.10	0.10
bbb	0.10	0.10	0.10
ccc	0.10	0.10	0.10
ddd	0.05	0.05	0.05
NOTES	1,2		
REF			
ISSUE			



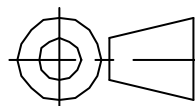
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MLP MICRO
PACKAGE OUTLINE
(EXPOSED & FUSED DUAL PAD)

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TABLE 3: COMMON HEIGHT DIMENSION


V-PROFILE HEIGHT

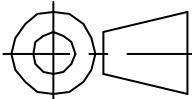
DIM SYMBOL	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0	0.025	0.05
A2	0.65	0.70	0.75
A3	0.15	0.20	0.25
θ	0°	10°	12°
NOTES	1,2		
REF			
ISSUE			

TABLE 4: COMMON TERMINAL DIMENSIONS

DIM	L2	K
PITCH	MAX	MIN
0.65	0.125	0.20
NOTES	5,11	5,11
REF		
ISSUE		

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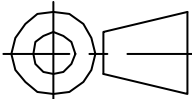
REV A	DWG NO: - MLPM-CPOD-0003			FILE:- MLPM-CPOD-0003-RevA
	APP'D	-		MLP MICRO PACKAGE OUTLINE (EXPOSED & FUSED DUAL PAD)
	CHECKED	CC YIP		
	DESIGNED	-		
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△ SUMMARY TABLE 5

BODY SIZE (mm)	LEAD PITCH (mm)	LEAD COUNT	VERY THIN PROFILE
3.00 X 2.00	0.65	8	VECC-E(DUAL PAD)

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	APP'D	-		MLP MICRO
	CHECKED	CC YIP		PACKAGE OUTLINE
	DESIGNED	-		(EXPOSED & FUSED DUAL PAD)
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SUMMARY TABLE 6 0.65mm PITCH VARIATION

SYMBOL									NOTE
b MIN	0.24								
b NOM	0.26								
b MAX	0.34								
D BSC	3.00								
D2 MIN	0.82								
D2 NOM	0.92								
D2 MAX	1.02								
D3 MIN	0.82								
D3 NOM	0.92								
D3 MAX	1.02								
D4 MIN	1.01								
D4 NOM	1.11								
D4 MAX	1.21								
D5 MIN	1.01								
D5 NOM	1.11								
D5 MAX	1.21								
E BSC	2.00								
E2 MIN	0.43								
E2 NOM	0.53								
E2 MAX	0.63								
E3 MIN	0.43								
E3 NOM	0.53								
E3 MAX	0.63								
E4 MIN	0.16								
E4 NOM	0.26								
E4 MAX	0.36								
L MIN	0.20								
L NOM	0.29								
L MAX	0.45								
L1 MIN	-								
L1 NOM	-								
L1 MAX	-								
N	8								3
ND	4								6
R REF	0.075								
R1 REF	0.075								
VARV	VECC-E(DUAL PAD)								
NOTE	1,2,9								
REF									
ISSUE									

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Note:

1. Dimensioning and tolerancing conform to ASME Y14.5M-1994.
2. All dimensions are in millimeters . All angles are in degrees.
3. N is the total number of terminals.

4. The terminal #1 identifier and terminal numbering convention shall conform to JESD 95-1 SPP-012. Details of terminal #1 identifier are optional , but must be located within the zone indicated. The terminal #1 identifier may be a molded, marked, or metalized features.

5. Dimension b applies to metalized terminal and is measured between 0.15 and 0.20mm from terminal tip.

6. ND refer to the maximum number of terminals on D side.

7. Depopulation of terminals is allowed and will be called out on the individual variation.


8. Variation VECC is shown for illustration only.

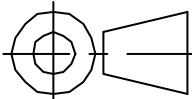
9. For a complete set of dimensions for each variation, see the individual variation and the common dimensions and tolerances on page 4 & 5.

10. Coplanarity applies to the exposed heat sink slug as well as the terminals.

11. Profile tolerance (aaa) will be applicable only to the plastic body, and not to the metalized features (such as the terminal tips and tie bars.) Metalized features may protrude a maximum of L2 from the plastic body profile.

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